



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-08-03
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Antonella Lanzafame	Representative Title	AMG Materials Declaration Champion)
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics :http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
ST1S40IDR	PZ07*UA27DDF	A	SH1A	2016-08-03
Amount	UoM	Unit type	ST ECOPACK Grade	
80.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	4.90,3.9,1.75	8	gull wing	
Comment	SO 08 .15 JEDEC			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList :REACH-20 June 2016				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	PZO7*UA27DDF					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	2.118	mg	supplier	die	Silicon (Si)	7440-21-3		2.004	mg	946176	25050
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.021	mg	9915	263
die (s)				supplier	metallization	Tungsten (W)	7440-33-7		0.017	mg	8026	213
die (s)				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.004	mg	1889	50
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.036	mg	16997	450
die (s)				supplier	passivation	Gamma-butyrolactone	96-48-0		0.012	mg	5666	150
die (s)				supplier	passivation	Polyhydroxyamide	55295-98-2		0.005	mg	2361	63
die (s)				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.002	mg	944	25
die (s)				supplier	back side metallization	Gold (Au)	7440-57-5		0.004	mg	1889	50
die (s)				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.012	mg	5666	150
die (s)				supplier	back side metallization	Vanadium (V)	7440-62-2		0.001	mg	472	13
Leadframe	Copper & its alloys	28.281	mg	supplier	alloy	Copper (Cu)	7440-50-8		27.331	mg	966409	341638
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.643	mg	22736	8038
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.039	mg	1379	488
Leadframe				supplier	alloy	Zinc (Zn)	7440-66-6		0.034	mg	1202	425
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		0.214	mg	7567	2675
Leadframe				supplier	metallization	Palladium (Pd)	7440-05-3		0.014	mg	495	175
Leadframe				supplier	metallization	Gold (Au)	7440-57-5		0.006	mg	212	75
Soft solder	Solder	0.72	mg	supplier	solder	Silver (Ag)	7440-22-4		0.655	mg	909722	8188
Soft solder				supplier	solder	acrylate	Proprietary		0.036	mg	50000	450
Soft solder				supplier	solder	Methacrylate	Proprietary		0.029	mg	40278	363
Bonding wire	Other inorganic materials	0.464		supplier	wire	Gold (Au)	7440-57-5		0.464	mg	1000000	5800
encapsulation	Other Organic Materials	48.417	mg	supplier	mold compound	Silica, vitreous	60676-86-0		35.045	mg	723816	438063
encapsulation				supplier	mold compound	Phenol resin	9003-35-4		2.766	mg	57129	34575
encapsulation				supplier	mold compound	Carbon black	1333-86-4		0.369	mg	7621	4613
encapsulation				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		4.703	mg	97135	58788
encapsulation				supplier	mold compound	Metal hydroxide	Proprietary		0.922	mg	19043	11525
encapsulation				supplier	mold compound	Others	Proprietary		2.306	mg	47628	28825
encapsulation				supplier	mold compound	Others	Proprietary		2.306	mg	47628	28825